WATTACH. 6-27-02 MANUSH PATENT Customer No. 22,852

Attorney Docket No. 04329.2270-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re	53(b) Continuation Application of:	
Shinsuke SAKAMOTO et al.		Group Art Unit: 2815
Application No.: 09/527,563) Examiner: E. Lee
Filed: March 16, 2000))
For:	SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND WIRING ARRANGING METHOD THEREOF)))

Assistant Commissioner for Patents Washington, DC 20231

Sir:

PRELIMINARY AMENDMENT

Prior to the examination of the above application, please amend this application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

On page 1, replace the paragraph beginning on line 11 with the following:

AI

The present invention relates to a semiconductor integrated circuit device making use of an area pad and a wiring arranging method thereof.

FINNEGAN HENDERSON FARABOW GARRETT& DUNNERLLP

On page 9, replace the paragraph beginning on line 22 with the following:

1300 l Street, NW AS Washington, DC 20005 202.408.4000 Fax 202.408.4400 www.finnegan.com As described above, the wiring length of the I/O slot can be shortened by the rewiring 24, 33 on the outermost periphery of the chip, and the delay in the signal